

	U	1	Document ID	Issue Date	Pages
1	<input type="checkbox"/>	<input type="checkbox"/>	US 20020179563 A1	20021205	7
2	<input type="checkbox"/>	<input type="checkbox"/>	US 6316370 B1	20011113	10
3	<input type="checkbox"/>	<input type="checkbox"/>	US 6027975 A	20000222	15
4	<input type="checkbox"/>	<input type="checkbox"/>	US 6020250 A	20000201	30
5	<input type="checkbox"/>	<input type="checkbox"/>	US 5969250 A	19991019	29
6	<input type="checkbox"/>	<input type="checkbox"/>	US 5801089 A	19980901	31
7	<input type="checkbox"/>	<input type="checkbox"/>	US 5760305 A	19980602	29
8	<input type="checkbox"/>	<input type="checkbox"/>	US 5605598 A	19970225	31

	Title	Current OR	Current XRef
1	Application of a strain-compensated heavily doped etch stop for silicon structure formation	216/2	
2	Method for etching doped polysilicon with high selectivity to undoped polysilicon	438/745	252/79.1; 252/79.2; 252/79.3; 252/79.4; 257/E21.309; 438/753; 438/756
3	Process for fabricating vertical transistors	438/268	257/E21.41; 257/E29.262; 438/138
4	Stacked devices	438/422	257/E27.064; 257/E29.113; 257/E29.114; 257/E29.124; 257/E29.13; 257/E29.137; 257/E29.151; 257/E29.275; 257/E29.286; 438/408; 438/409; 438/589
5	Micromechanical accelerometer having a peripherally suspended proof mass	73/514.38	73/514.24
6	Method of forming stacked devices	438/589	148/DIG.164; 257/E27.064; 257/E29.13; 257/E29.137; 257/E29.286; 438/259; 438/270
7	Monolithic micromechanical vibrating beam accelerometer with trimmable resonant frequency	73/514.15	257/417; 257/419; 438/52
8	Monolithic micromechanical vibrating beam accelerometer with trimmable resonant frequency	438/50	216/2; 216/62; 438/455

	Retrieval Classif	Inventor	S	C	P	2	3	4	5
1		Horning, Robert D. et al.	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
2		Mercaldi, Garry A. et al.	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
3		Hergenrother, John M. et al.	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
4		Kenney, Donald McAlpine	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
5		Greiff, Paul	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
6		Kenney, Donald McAlpine	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
7		Greiff, Paul	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
8		Greiff, Paul	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>

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1	US 20020179563	<input type="checkbox"/>
2	US 6316370	<input type="checkbox"/>
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4	US 6020250	<input type="checkbox"/>
5	US 5969250	<input type="checkbox"/>
6	US 5801089	<input type="checkbox"/>
7	US 5760305	<input type="checkbox"/>
8	US 5605598	<input type="checkbox"/>

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9	<input type="checkbox"/>	<input type="checkbox"/>	US 5583368 A	19961210	32
10	<input type="checkbox"/>	<input type="checkbox"/>	US 4978421 A	19901218	9

	Title	Current OR	Current XRef
9	Stacked devices	257/621	257/302; 257/330; 257/334; 257/513; 257/514; 257/520; 257/521; 257/559; 257/622; 257/67; 257/E27.064; 257/E29.113; 257/E29.114; 257/E29.124; 257/E29.13; 257/E29.151; 257/E29.275; 257/E29.286
10	Monolithic silicon membrane device fabrication process	216/2	438/691; 438/753; 438/756; 438/757; 438/977

	Retrieval Classif	Inventor	S	C	P	2	3	4	5
9		Kenney, Donald M.	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
10		Bassous, Ernest et al.	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>

L Number	Hits	Search Text	DB	Time stamp
1	17826	(Substrate) and (lightly with doped)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/04/10 08:17
8	985	(p near+) and (boron and germanium)and (heavily near doped)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/04/10 08:19
15	1119	anisotropic near etchants	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/04/10 08:20
22	512	((Substrate) and (lightly with doped)) and ((p near+) and (boron and germanium)and (heavily near doped))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/04/10 08:20
29	10	(anisotropic near etchants) and (((Substrate) and (lightly with doped)) and ((p near+) and (boron and germanium)and (heavily near doped)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/04/10 08:20

L Number	Hits	Search Text	DB	Time stamp
1	2	("5583638").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/18 15:10
8	2	("6316370").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/18 15:11
15	2	("6027975").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/18 15:12
22	2	("6020250").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/18 15:13
29	2	("5969250").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/18 15:14
36	0	("(piezoresistor) and (resonant adj microbeams)").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/18 15:14
43	0	("(piezoresistors)").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/18 15:15
50	0	("(resonant near microbeams)").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/18 15:15
57	748	(piezoresistor)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/18 15:16
64	16	(piezoresistor)and (resonant adj microbeams)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/18 15:18
71	1	(piezoresistor)and (resonant adj microbeams)and (cantilevered near accelerometer)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/18 15:19
85	1	((piezoresistor)and (resonant adj microbeams)) and (cantilevered near accelerometer)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/18 15:19
78	21	cantilevered near accelerometer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/18 15:19